**CNSE NanoFab Tool Calibration Form**

**DATE: \_\_2/10/2016\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_**

**Tool Description: \_\_\_\_Karl Suss MA-6 Mask Aligner\_\_\_**

**Test: S-1813 Resist Exposure/Dev. Critical Dimension**

**Run Parameters:**

**Sample size: 4” silicon wafer**

**Material: S-1813 Photoresist**

**Spin Speed: 4000 RPM**

**Bake Temp: 115C on hotplate**

**Bake Time: 60 sec.**

**Exposure Tool: Suss MA-6**

**Exposure Mode: Vacuum Contact**

**Exposure Time: 7 sec.**

**Mask: Resolution 1**

**Developer/Time: AZ 400K 1:4/ 60 sec**

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**Results:**

**CD: 10 um L/S**

**CD Measured (4 quadrants average) : 10.0125 um**

**Engineer: CNSE Staff\_Frank Lee\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_**